

Fast Rectifiers (Glass Passivated)

EGF1A, EGF1B, EGF1C, EGF1D

Features

- Low Forward Voltage Drop
- Low Profile Package
- Fast Switching for High Efficiency
- These Devices are Pb-Free, Halide Free and are RoHS Compliant

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

		Value				
Symbol	Parameter	1A 1B 1C 1D		Unit		
V_{RRM}	Maximum Repetitive Reverse Voltage	50	50 100 150			V
I _{F(AV)}	Average Rectified Forward Current, @ $T_L = 100^{\circ}C$	1.0			Α	
I _{FSM}	Non-repetitive Peak Forward Surge Current 8.3 ms Single Half-Sine-Wave	30			Α	
T _{stg}	Storage Temperature Range	-65 to +175		°C		
T_J	Operating Junction Temperature	-65 to +175		°C		

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
V_{RRM}	Maximum Repetitive Reverse Voltage	200	V
P_{D}	Power Dissipation	2.0	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient*	85	°C/W
$R_{ heta JL}$	Thermal Resistance, Junction to Lead*	30	°C/W

^{*}Device mounted on FR-4 PCB 0.013 mm.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

		Device				
Symbol	Parameter	1A	1B	1C	1D	Unit
V _F	Forward Voltage @ 1.0 A	1.0			V	
t _{rr}	Reverse Recovery Time $I_F = 0.5 \text{ A}, I_R = 1.0 \text{ A}, I_{RR} = 0.25 \text{ A}$	50			ns	
I _R	Reverse Current @ Rated V_R $T_A = 25$ °C $T_A = 100$ °C	10 100		μ Α μ Α		
C _T	Total Capacitance $V_R = 4.0 \text{ V}, f = 1.0 \text{ MHz}$	15		pF		

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.



COLOR BAND DENOTES CATHODE

SMA (DO-214AC)

CASE 403AE

MARKING DIAGRAM



\$Y = Logo

&Z = Assembly Plant Code &3 = 3-Digit Date Code

EGF1x = Specific Device Code (x = A, B, C, D)

ORDERING INFORMATION

Device	Package	Shipping [†]
EGF1A	SMA	7500 / Tape &
EGF1B	(Pb–Free, Halide Free)	Reel
EGF1C		
EGF1D		

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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TYPICAL CHARACTERISTICS

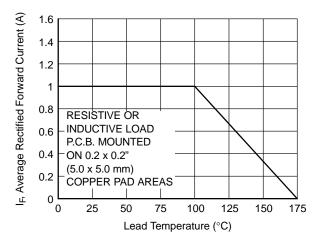


Figure 1. Forward Current Derating Curve

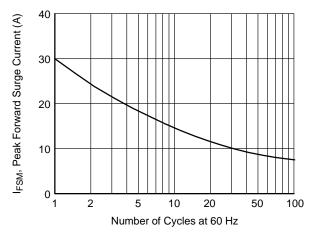


Figure 3. Non-Repetitive Surge Current

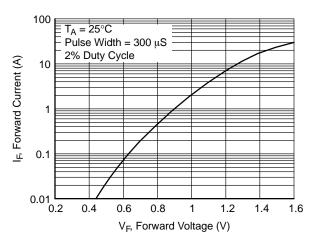


Figure 2. Forward Voltage Characteristics

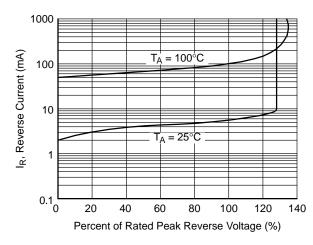


Figure 4. Reverse Current vs. Reverse Voltage

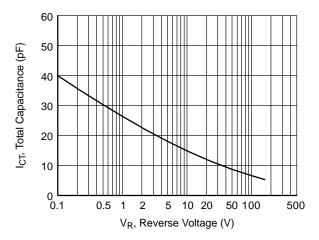
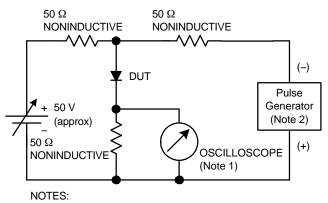


Figure 5. Total Capacitance

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REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM



- 1. Rise time = 7.0 ns max; Input impedance = 1.0 M Ω 22 pF.
- 2. Rise time = 10 ns max; Source impedance = 50 Ω .

Figure 6. Test Circuit Diagram

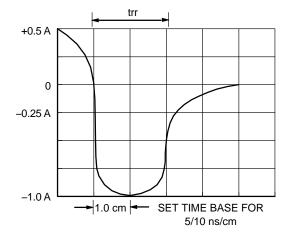
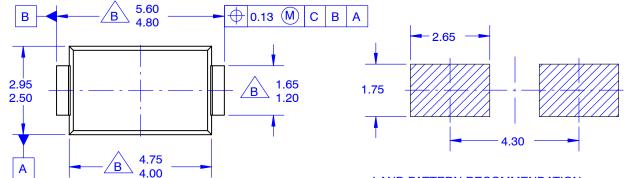


Figure 7. Reverse Recovery Time Characteristic

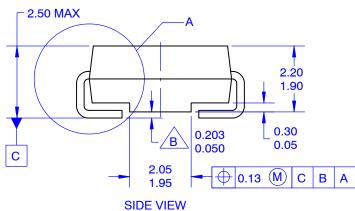
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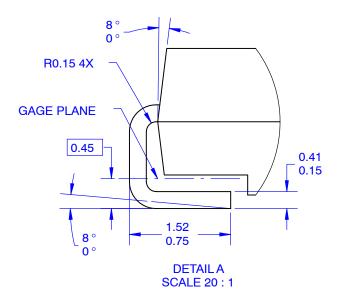
TOP VIEW

LAND PATTERN RECOMMENDATION



NOTES:

- A. EXCEPT WHERE NOTED, CONFORMS ^ TO JEDEC DO214 VARIATION AC.
- B DOES NOT COMPLY JEDEC STANDARD VALUE.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.
- D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- E. DIMENSIONS AND TOLERANCE AS PER ASME Y14.5–2009.
- E. LAND PATTERN STD. DIOM5025X231M



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